

Harvatek Surface Mount CHIP LEDs Data Sheet B31G3BGR-20C0001Q3U1930



Offici	Official Product HT Part No. B31G3BGR-20C0001Q3U1930 Customer Part No.						
Tenta	tive Product	*******	******				
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- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- 2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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Product Specifications

Specification	Material	Quantity
R: 540-1150 mcd		
G: 800-1840 mcd		
B: 210-550 mcd		
@20mA/ T _S = 25°C; Tolerance: <u>+</u> 10%		
R: 620.0-630.0 nm		
G: 517.0-527.0 nm		
B: 462.0-472.0 nm		
@20mA/ T _S = 25°C ;Tolerance: <u>+</u> 0.5nm		
R: 1.8-2.4 V		
G: 2.6-3.4 V		
B: 2.6-3.4 V		
@20mA/ T_S = 25°C ; Tolerance: \pm 0.05V		
< 1 μA @ V _R = 5V		
Clear	Ероху	
EIA 481-1A specs	Conductive black tape	3000ea/reel
EIA 481-1A specs	Conductive black	
HT standard	Paper	
230x250mm	Aluminum laminated bag/ no-zipper	One reel per bag
HT standard	Paper	Non-specified
	R: $540\text{-}1150 \text{ mcd}$ G: $800\text{-}1840 \text{ mcd}$ B: $210\text{-}550 \text{ mcd}$ @ $20\text{mA}/\text{T}_\text{S}=25^{\circ}\text{C}$; Tolerance: $\pm 10\%$ R: $620.0\text{-}630.0 \text{ nm}$ G: $517.0\text{-}527.0 \text{ nm}$ B: $462.0\text{-}472.0 \text{ nm}$ @ $20\text{mA}/\text{T}_\text{S}=25^{\circ}\text{C}$; Tolerance: $\pm 0.5\text{nm}$ R: $1.8\text{-}2.4 \text{ V}$ G: $2.6\text{-}3.4 \text{ V}$ B: $2.6\text{-}3.4 \text{ V}$ @ $20\text{mA}/\text{T}_\text{S}=25^{\circ}\text{C}$; Tolerance: $\pm 0.05\text{V}$ < $1 \text{ µA} \text{ @ V}_\text{R} = 5\text{V}$ Clear EIA $481\text{-}1\text{A} \text{ specs}$ EIA $481\text{-}1\text{A} \text{ specs}$ HT standard $230\text{x}250\text{mm}$	$R: 540\text{-}1150 \text{mcd} \\ G: 800\text{-}1840 \text{mcd} \\ B: 210\text{-}550 \text{mcd} \\ @20\text{mA}/T_\text{S} = 25^\circ\text{C}; \text{Tolerance:} \pm 10\% \\ R: 620.0\text{-}630.0 \text{nm} \\ G: 517.0\text{-}527.0 \text{nm} \\ B: 462.0\text{-}472.0 \text{nm} \\ @20\text{mA}/T_\text{S} = 25^\circ\text{C}; \text{Tolerance:} \pm 0.5\text{nm} \\ R: 1.8\text{-}2.4 \text{V} \\ G: 2.6\text{-}3.4 \text{V} \\ B: 2.6\text{-}3.4 \text{V} \\ @20\text{mA}/T_\text{S} = 25^\circ\text{C}; \text{Tolerance:} \pm 0.05\text{V} \\ < 1 \text{\muA} @\text{V}_\text{R} = 5\text{V} \\ \text{Clear} \qquad \qquad \text{Epoxy} \\ \text{EIA 481-1A specs} \qquad \qquad \text{Conductive black tape} \\ \text{EIA 481-1A specs} \qquad \qquad \text{Conductive black} \\ \text{HT standard} \qquad \qquad \text{Paper} \\ 230x250\text{mm} \qquad \qquad \text{Aluminum laminated bag/ no-zipper} \\ \end{tabular}$

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

Note: This is shipped test conditions

*Remarks: This product should be operated in forward bias. If a reverse voltage is continuously applied to the product, such operation can cause migration resulting in LED damage.

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlGaInP, GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. ESD precaution must

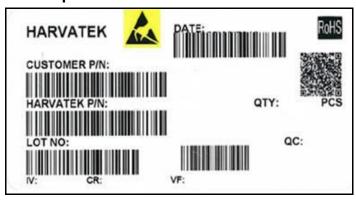
be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

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Label Specifications



Harvatek P/N:

B 31G 3 BGR- 20C- 0001 Q3

Product	Package	Dice Qty	Color	Current	Series Number	Taping
PCB	3.2(L)x1.5(W)x1.0(H) mm	3:Tri	BGR : RGB(Full	20mA	X001~XZZZ	1.Taping style
			Color)			2. Qty

Lot No.:

1	2	3	4	5	6	7	8	9	10
Ε	1	Α	1	Α	2	2	L	1	2
Cod	te 1 2	Code 3	Code 4	Code 5	Code 6	Code 7	Code 8	Code 9	Code 10
		Mfg. Year	Mfg. Month	Mfg. Date	Consecuti	ve number		Special code	8
Internal Tr	acing Code	2020-L 2021-M 2022-P 2023-Q 2026-T 2027-V 2030-Y 2031-Z	1:Jan. 2:Feb. A:Oct. B:Nov. C:Dec.	1:A 2:B 3:C 26:Z 27:7 28:8 29:9 30:3 31:4	01-	-zz		000-ZZZ	

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Specifications Range

Luminous Intensity (Iv) Bin:

Luminous Intensity (Iv) Bin:R/G/B@20mA

	HT-B31G3BGR Series									
	IV									
	Red			Green			Blue			
KR2	540	790	KG2	1150	1840	KB2	210	340		
KR3	KR3 790 1150 KB3 340 550									

Note: It maintains a tolerance of ±10% on luminous intensity

Dominant Wavelength (λD) Bin:

HT-B31G3 BGR Series											
	WD										
	Red			Green			Blue				
R1	620	625	G1	G1 517 522			462	467			
R2	R2 625 630 G2 522 527 B2 467 472										

Note: It maintains a tolerance of \pm 0.5nm on color

Forward Voltage (Vf) Bin:

	HT-B31G3BGR Series									
	VF									
	Red Green Blue									
F	F 1.8 2.4 G38 2.6 3.4 G38 2.6 3.4									

Note: It maintains a tolerance of $\pm 0.05 \text{V}$ on forward voltage measurements

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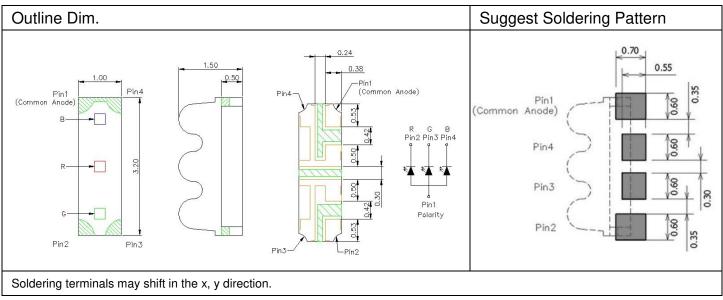
Product Features

Electro-Optical Characteristics

			1					(1 _S	oldering , 25 °C)
Carios	Emitting Color	o. M		(V)	Wa	velength λ	(nm)	I _V (mcd)	Viewing
Series Emitting Color		Material	typ	max	λ_{D}	λ_{P}	Δλ	Typical	Angle $2\theta \frac{1}{2}$
	Red	AllnGaP	2.0	2.4	620	630	20	950	110
B31G3BGR-20	Green	InGaN	2.6	3.4	526	518	30	1500	110
	Blue	InGaN	2.6	3.4	468	463	20	330	110

Package Outline Dimension and Recommended Soldering Pattern for Reflow Soldering

(Unit:mm Tolerance: +/-0.1)



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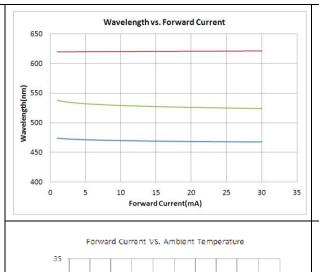
(T_{Soldering} 25 °C)

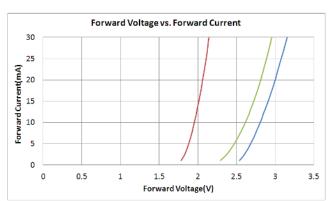
Absolute Maximum Ratings

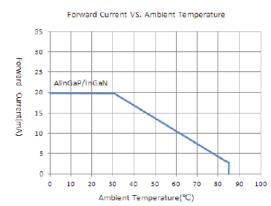
Series	P _D (mW)	V _R (V)	I _F (mA)	I _{FP} (mA)*	Top (°C)
Color	Power Dissipation	Reverse		Pulse Forward	Operating
Coloi	lor Power Dissipation Voltage		Forward Current	Current	Temperature
Red	45	5	20	≦100	
Green	56	5	20	≦80	-40~85
Blue	60	5	20	≦80	

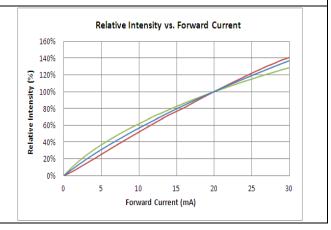
^{*}Condition for I_{FP} is pulse of 1/10 duty and 0.1 msec width

Characteristics of B31G3BGR -20C





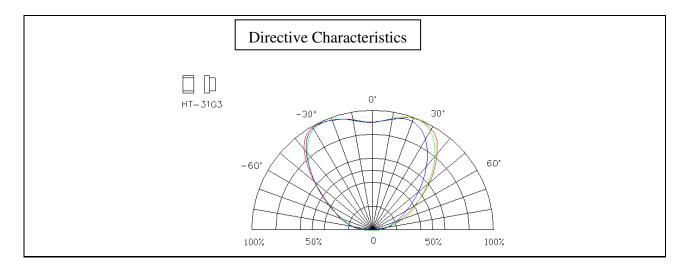




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^{*}Remarks:This product should be operated in forward bias.If a reverse voltage is continuously applied to the product, such operation can cause migration resulting in LED damage.





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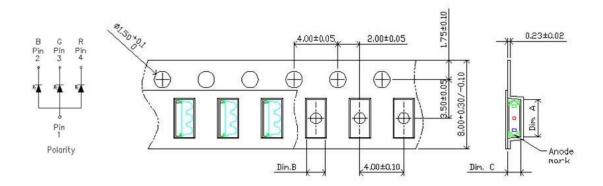
Precaution for Use

- 1. The chips should not be used directly in any type of fluid such as water, oil, organic solvent, etc.
- 2. When the LEDs are illuminating, the maximum ambient temperature should be first considered before operation.
- 3. LEDs must be stored in a clean environment. A sealed container with a nitrogen atmosphere is necessary if the storage period is over 3 months after shipping.
- 4. The LEDs must be used within 72 hours after unpacked. Unused products must be repacked in an anti-electrostatic package, folded to close any opening and then stored in a dry and cool space.
- 5. The appearance and specifications of the products may be modified for improvement without further notice.
- 6. The LEDs are sensitive to the static electricity and surge. It is strongly recommended to use a grounded wrist band and anti-electrostatic glove when handling the LEDs.If a voltage over the absolute maximum rating is applied to LEDs, it will damage LEDs.Damaged LEDs will show some abnormal characteristics such as remarkable increase of leak current, lower turn-on voltage and getting unlit at low current.

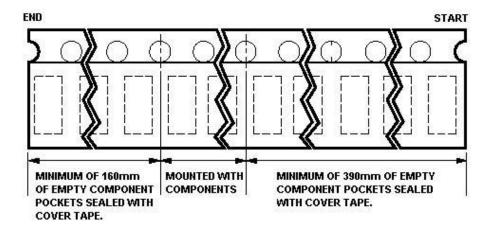
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Packaging Tape Dimension



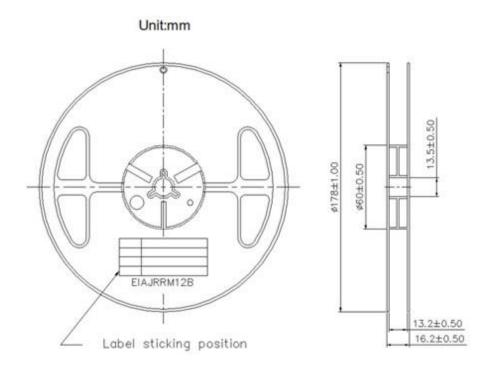
Dim. A	Dim. B	Dim. C	Qty/Reel
3.43±0.10	1.73±0.10	1.15±0.10	3K



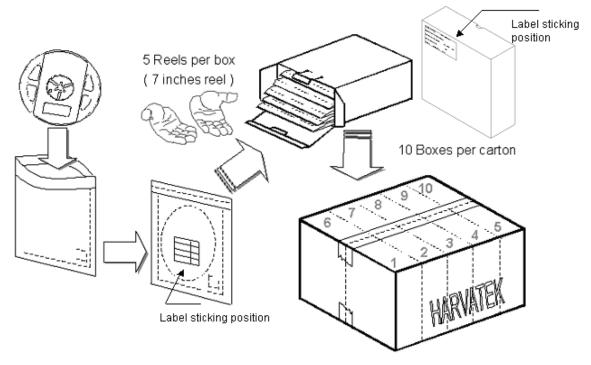
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Reel Dimension



Packing



5 boxes per carton is available depending on shipment quantity.

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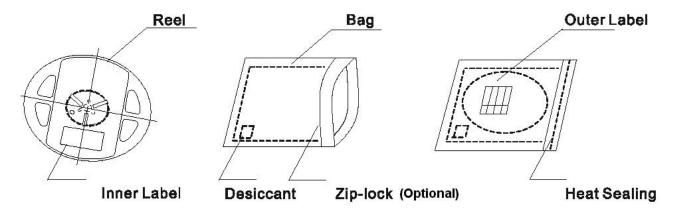


Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

A humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



Baking

Baking before soldering is recommended when the package has been unsealed for 72 hours. The conditions are as followings:

- 1. $60\pm3^{\circ}$ C × $(12\sim24\text{hrs})$ and <5%RH, taped reel type.
- 2. $100\pm3^{\circ}$ C ×(45min~1hr), bulk type.
- 3. $130\pm3^{\circ}$ C ×(15min~30min), bulk type.

Precautions

- 1. Avoid exposure to moisture at all times during transportation or storage.
- 2. Anti-Static precaution must be taken when handling GaN, InGaN, and AlGaInP products.
- 3. It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage beyond the specified limit.
- 4. Avoid operation beyond the limits as specified by the absolute maximum ratings.
- 5. Avoid direct contact with the surface through which the LED emits light.
- 6. If possible, assemble the unit in a clean room or dust-free environment.

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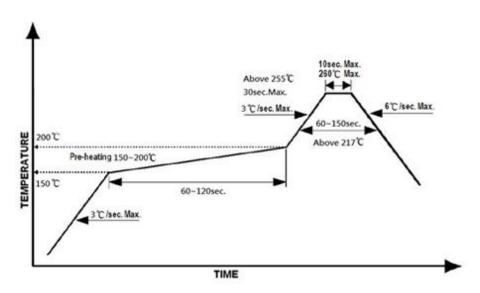


Reflow Soldering

Recommend soldering paste specifications:

- 1. Operating temp.: Above 217°C ,60-150 sec.
- 2. Peak temp.:260 °C Max.,10sec Max.
- 3. Reflow soldering should not be done more than two times.
- 4. Never attempt next process until the component is cooled down to room temperature after reflow.
- 5. The recommended reflow soldering profile (measured on the surface of the LED terminal) is as following:

Lead-free Solder Profile



Reworking

- Rework should be completed within 5 seconds under 260 ℃.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultrasonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

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Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electric-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

Revise History

	-	T	
Rev.	Descriptions	Date	Page
1.0	-	02/23/2017	-
1.1	Modify soldering pattern	03/22/2018	P7
1.2	Modify the opening time	11/20/2018	P10 · P13
1.3	Modify the Absolute Maximum Ratings	06/09/2022	P8
1.4	Added operating temperature	06/14/2022	P8
1.5	Modify the Pulse Forward Current	06/23/2022	P8

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